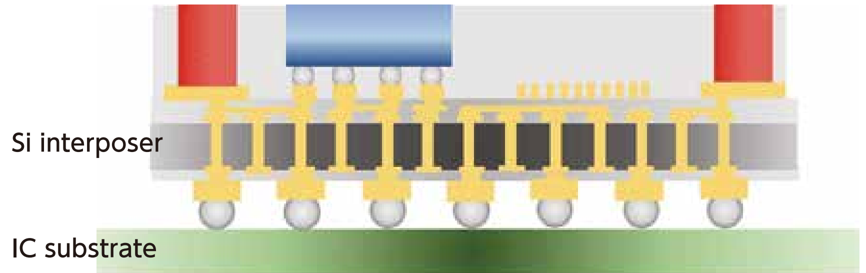
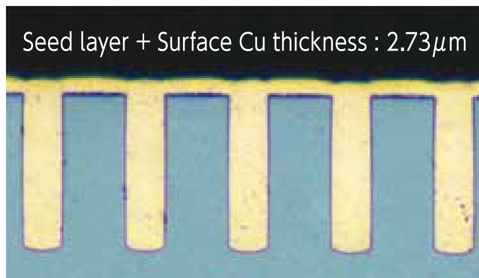
Acid copper plating additices for wafer

TORYZA LCN series



TSV filling

TORYZA LCN SV

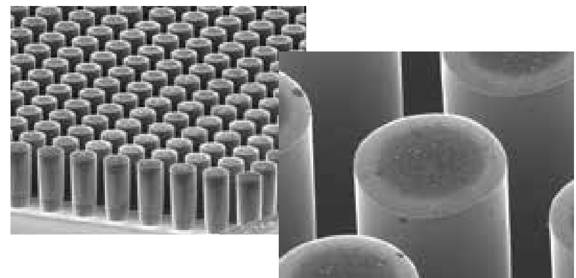


Current density : 0.2A/dm², via diameter : 7μm, via depth : 25μm

Realize high-aspect ratio via filling by small thickness

To FO-PLP/WLP, high current density for Cu pillar formation

TORYZA LCN SP



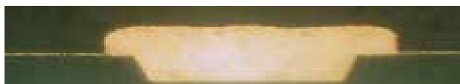
Current density : 8A/dm², pillar diameter : 15μm, pillar height : 65μm

Flat surface, high thickness uniformity

Micro-bump formation

TORYZA LCN SD

For micro-bump



1.5A/dm², 15 min, via diameter : 40μm, via depth : 5μm

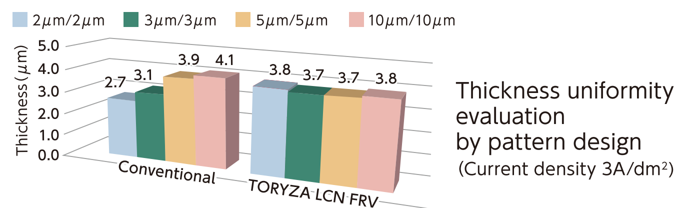
For trench

1.5A/dm², 60 min
Trench width 50μm,
depth 55μm

For low aspect ratio micro-bump and trench filling

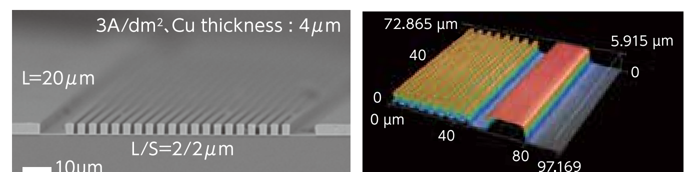
RDL formation

TORYZA LCN FRV



Thickness uniformity evaluation by pattern design (Current density 3A/dm²)

High thickness uniformity, Can use for L/S=2/2μm



High rectangularity of patterns

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